

Title (en)
DIODE LASER

Title (de)
DIODENLASER

Title (fr)
LASER À DIODES

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Application
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Abstract (en)
[origin: WO2019086619A1] The invention relates to a laser assembly (1) comprising a diode laser bar (2), a heat sink (4) and at least one cover (7). The laser bar is located between the heat sink and the cover. The heat sink and/or the cover is/are coated with nanowires (16) or nanotubes via which the contact between the laser bar and the heat sink and/or the cover is established.

IPC 8 full level
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